

L Numb r	Hits	Search Text	DB	Tim stamp
3	0	"09866244"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:37
4	24	(US-5506499-\$ or US-5554940-\$ or US-6313541-\$ or US-5900643-\$ or US-5891745-\$ or US-6373143-\$ or US-6348742-\$ or US-5783868-\$ or US-6068892-\$ or US-6008061-\$ or US-5923047-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6342402-\$ or US-5886414-\$ or US-5719449-\$ or US-6091155-\$ or US-6426531-\$ or US-6291899-\$ or US-4951098-\$).did. or (US-20010001541-\$ or US-20020017729-\$).did. or (US-5506499-\$).did.	USPAT; US-PGPUB; DERWENT	2003/10/22 12:37
7	11	((US-5506499-\$ or US-5554940-\$ or US-6313541-\$ or US-5900643-\$ or US-5891745-\$ or US-6373143-\$ or US-6348742-\$ or US-5783868-\$ or US-6068892-\$ or US-6008061-\$ or US-5923047-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6342402-\$ or US-5886414-\$ or US-5719449-\$ or US-6091155-\$ or US-6426531-\$ or US-6291899-\$ or US-4951098-\$).did. or (US-20010001541-\$ or US-20020017729-\$).did. or (US-5506499-\$).did.) and 257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:37
8	16	(resin near5 encapsulates near5 chip near5 wire) and (test or tested or testing or probe or probing or probed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:49
9	0	resin near encapsulates near chip near wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:49
10	229	(bond or bonding) near5 (pad) near5 (test or testing or probe or probing) near5 (wire or wiring or connection).ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:49
13	74	((b nd or b nding) near3 (pad) near3 (test r testing or pr be or probing) near3 (wire r wiring or c nn cti n)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:49

14	6	(((str ngth or str ng r str nger) adj ((bond or bonding) adj (wir or wiring))) and ((b nd r bonding) adj pad)) and (test or t ted r testing r tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:49
15	38	(((connection or wire or wiring or mounting) adj pad) and ((test or probe or testing) adj pad)).clm,ab,ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:49
16	1	((((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab,)) and umeda	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:50
17	14	(((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (probe or probing or probed or test or testing or tested or tester) near5 (section or region or part)).clm,ti,ab.) and pad.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/22 12:50